

NCE N-Channel Super Trench Power MOSFET

Description

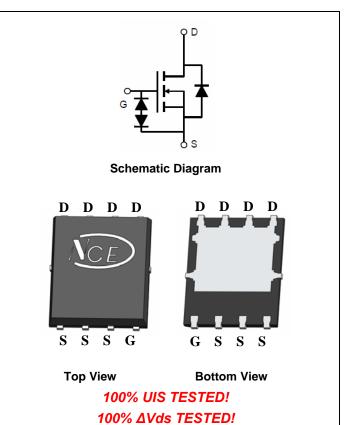
The NCEP4085EG uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification. It is ESD protested.

General Features

- V_{DS} =40V, I_D =85A $R_{DS(ON)}$ =3.7mΩ (typical) @ V_{GS} =10V $R_{DS(ON)}$ =5.0mΩ (typical) @ V_{GS} =4.5V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating
- 100% UIS tested
- ESD protection : HBM Class 2

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP4085EG	NCEP4085EG	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	40	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous (Silicon Limited)	I _D	85	Α	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	59.5	А	
Pulsed Drain Current (Package Limited)	I _{DM}	260	А	
Maximum Power Dissipation	P _D	65	W	
Derating factor		0.52	W/℃	
Single pulse avalanche energy (Note 5)	E _{AS}	288	mJ	
Operating Junction and Storage Temperature Range	T_{J},T_{STG}	-55 To 150	$^{\circ}$ C	

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	R _{eJC}	1.92	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	40		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±10	μA
On Characteristics (Note 3)			•			•
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.0	1.5	2.2	V
Drain-Source On-State Resistance	-	V _{GS} =10V, I _D =20A	-	3.7	4.0	mΩ
Dialii-Source Oil-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	5.0	5.5	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A		40	-	S
Dynamic Characteristics (Note4)			•			•
Input Capacitance	C _{lss}	V 00V/V 0V/	-	2100	2600	PF
Output Capacitance	Coss	V_{DS} =20 V , V_{GS} =0 V , F=1.0MHz	-	639	800	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIHZ	-	23.6	29	PF
Switching Characteristics (Note 4)			•			•
Turn-on Delay Time	t _{d(on)}		-	7.5	-	nS
Turn-on Rise Time	t _r	V_{DD} =20 V , I_{D} =20 A	-	4	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	26	-	nS
Turn-Off Fall Time	t _f		-	3.3	-	nS
Total Gate Charge	Qg		-	34.3	47	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=20V,I_{D}=20A,$	-	7.1		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	3.5		nC
Drain-Source Diode Characteristics					<u></u>	
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =85A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	85	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = I_S$	-	19	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 500A/\mu s^{(Note3)}$	-	40	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =20V,V $_{\text{G}}$ =10V,L=0.5mH,Rg=25 Ω





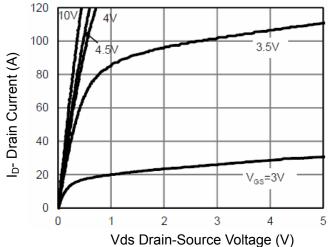


Figure 1 Output Characteristics

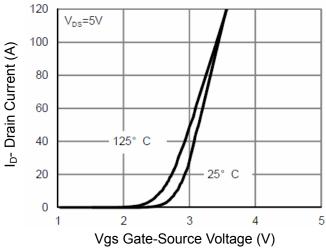


Figure 2 Transfer Characteristics

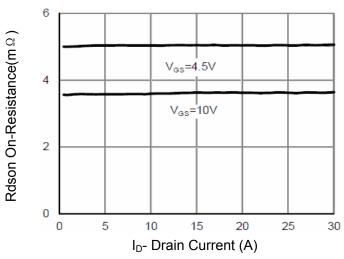


Figure 3 Rdson- Drain Current

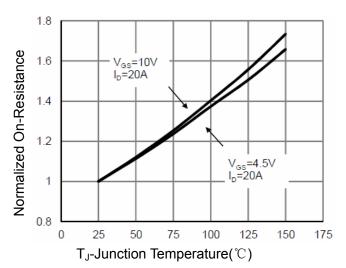


Figure 4 Rdson-Junction Temperature

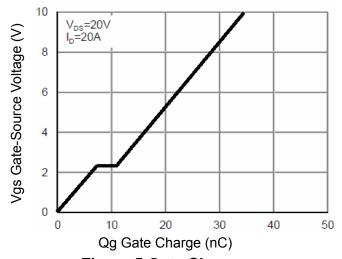


Figure 5 Gate Charge

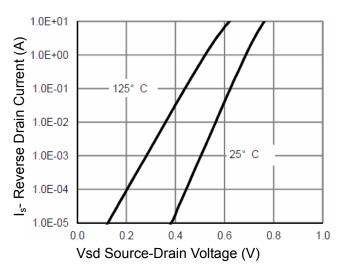
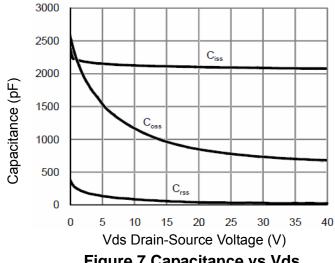


Figure 6 Source- Drain Diode Forward







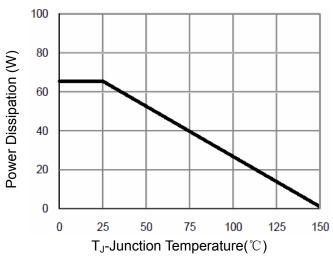


Figure 9 Power De-rating

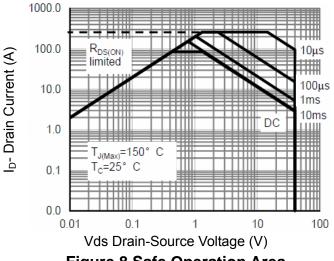


Figure 8 Safe Operation Area

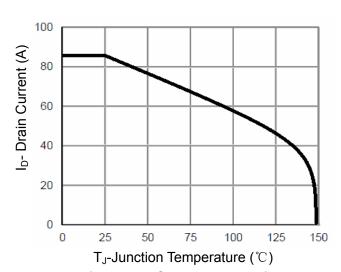


Figure 10 Current De-rating

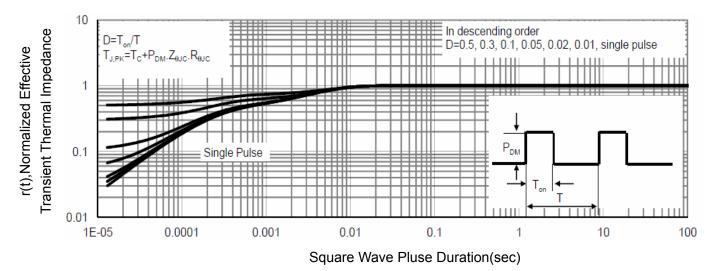
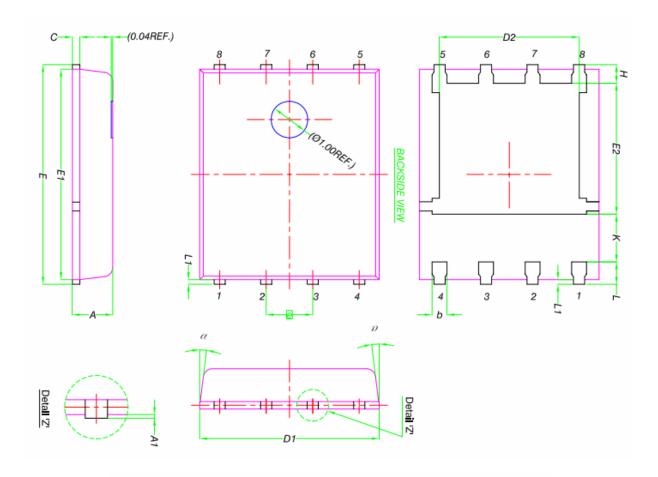


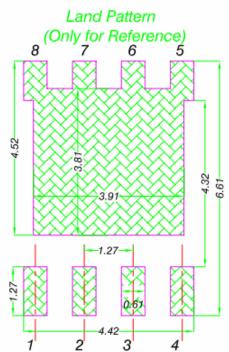
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



5	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	0.90 1.00		1.10		
A1	0 -		0.05		
b	0.33	0.33 0.41			
С	0.20 0.25		0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10		
E1	5.70	5.75	5.80		
E2	3.38	3.58	3.78		
е	1.27 BSC				
Н	0.41	0.51	0.61		
К	1.10	-	-		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	<i>0</i> °	-	12°		





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